

DTU19P10C www.din-tek.jp

RoHS

COMPLIANT

# P-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY			
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω) I <sub>D</sub> (A)		Q <sub>g</sub> (Typ.)
- 100	0.035 at V <sub>GS</sub> = - 10 V	- 39	11.7
	0.038 at V <sub>GS</sub> = - 4.5 V	- 32	11.7

TO-252

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G D Top View

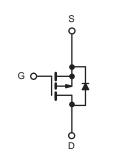
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### **FEATURES**

- DT-Trench Power MOSFET
- 100 %  $\rm R_g$  and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

#### **APPLICATIONS**

- Power Switch
- DC/DC Converters



P-Channel MOSFET

ABSOLUTE MAXIMUM RATING	<b>S</b> T <sub>C</sub> = 25 °C, unless othe	rwise noted			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	- 100	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	v	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C	1	- 39		
	T <sub>C</sub> = 70 °C	. I <sub>D</sub>	- 33.1		
Pulsed Drain Current		I <sub>DM</sub>	- 142	- A	
Avalanche Current		I <sub>AS</sub>	- 28		
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	25.7	mJ	
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C	P <sub>D</sub>	88.4 <sup>b</sup>	w	
	T <sub>A</sub> = 25 °C <sup>c</sup>		3.9		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	50	°C/W	
Junction-to-Case (Drain)	R <sub>thJC</sub>	2.2	0/11	

Notes:

a. Duty cycle  $\leq$  1 %.

b. See SOA curve for voltage derating.

c. When Mounted on 1" square PCB (FR-4 material).

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{DS} = 0 V, I_D = -250 \mu A$	- 100			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1		- 3.5	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 250	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 100 V, V <sub>GS</sub> = 0 V			- 1	μA
		$V_{DS}$ = - 100 V, $V_{GS}$ = 0 V, $T_{J}$ = 125 °C			- 50	
		V <sub>DS</sub> = - 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C			- 250	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \leq$ - 10 V, $V_{GS}$ = - 10 V	- 142			А
	D	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 3.6 A		0.035	0.040	Ω
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 3.4 A		0.038	0.045	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 3.6 A		17		S
Dynamic <sup>b</sup>	•	·			· · · · · · ·	
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = - 50 V, f = 1 MHz		922		pF
Output Capacitance	C <sub>oss</sub>			85		
Reverse Transfer Capacitance	C <sub>rss</sub>	]		61		
Total Cata Charge		$V_{DS} = -50 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -3.6 \text{ A}$		28.2		nC
Total Gate Charge <sup>c</sup>	Qg			19.3		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS}$ = - 50 V, $V_{GS}$ = - 4.5 V, $I_{D}$ = - 3.6 A		5.1		
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			5.4		
Gate Resistance	Rg	f = 1 MHz	1.2	5.7	11.5	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			7	14	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = - 50 V, $R_L$ = 17.2 $\Omega$		12	18	ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_{\rm D} \cong$ - 2.9 A, $V_{\rm GEN}$ = - 10 V, $R_{\rm g}$ = 1 $\Omega$		33	50	
Fall Time <sup>c</sup>	t <sub>f</sub>			9	18	
Drain-Source Body Diode Ratings a	nd Characteri	stics T <sub>C</sub> = 25 °C <sup>b</sup>				
Continuous Current	۱ <sub>S</sub>				- 39	A
Pulsed Current	I <sub>SM</sub>				-142	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = - 2.9 A, V <sub>GS</sub> = 0 V		- 0.8	- 1.5	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = - 2.9 A, dl/dt = 100 A/μs		50	75	ns
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>			- 4	- 6	Α
Reverse Recovery Charge	Q <sub>rr</sub>	1 1		98	147	nC

Notes:

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

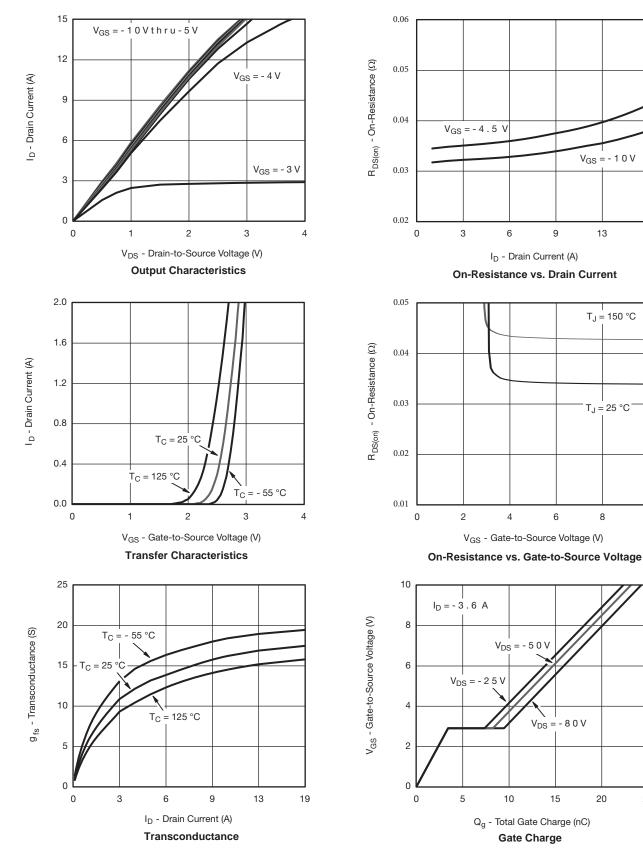


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-10V

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### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

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#### 100 - 1.1 - 1.4 I<sub>S</sub> - Source Current (A) T<sub>J</sub> = 150 °C $I_D = 250 \ \mu A$ 10 $V_{GS(th)}$ (V) - 1.7 T<sub>J</sub> = 25 °C 1 - 2.0 0.1 - 2.3 - 50 - 25 0 25 50 75 150 0.0 0.3 0.6 0.9 1.2 100 125 V<sub>SD</sub> - Source-to-Drain Voltage (V) T<sub>J</sub> - Temperature (°C) Source-Drain Diode Forward Voltage **Threshold Voltage** 1600 - 100 V<sub>DS</sub> - Drain-to-Source Voltage (V) - 106 1200 Ciss I<sub>D</sub> = 250 μA C - Capacitance (pF) - 112 800 - 118 400 - 124 Coss 0 - 130 20 40 60 80 100 - 25 0 25 50 75 100 150 0 - 50 125 T<sub>J</sub> - Junction Temperature (°C) V<sub>DS</sub> - Drain-to-Source Voltage (V) Drain Source Breakdown vs. Junction Temperature Capacitance 2.1 40 $V_{GS}$ 0 I<sub>D</sub> = - 3.6 A 32 1.7 R<sub>DS(on)</sub> - On-Resistance I<sub>D</sub> - Drain Current (A) (Normalized) 24 $V_{GS} =$ 4.5 V 1.3 16 0.9 8 0.5 0 - 25 - 50 0 25 50 75 100 125 150 0 25 50 75 100 125 150 T<sub>J</sub> - Junction Temperature (°C) T<sub>C</sub> - Case Temperature (°C) **On-Resistance vs. Junction Temperature Current Derating**



I<sub>DAV</sub> (A)

100

10

1 – 10<sup>-6</sup>

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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

T<sub>J</sub> = 25 °C

T<sub>J</sub> = 150 °C

10<sup>-5</sup>

#### www.din-tek.jp 100 Limited by R<sub>DS(on)</sub> 39 I<sub>D</sub> - Drain Current (A) 100 µs 1 ms 1 10 ms 100 ms 1 s, 10 s, DC T<sub>A</sub> = 25 °C Single Pulse 0.1 **BVDSS** Limited 0.01 10-1 0.1 1 10 100 V<sub>DS</sub> - Drain-to-Source Voltage (V) \* $V_{GS}$ > minimum $V_{GS}$ at which $R_{DS(on)}$ is specified

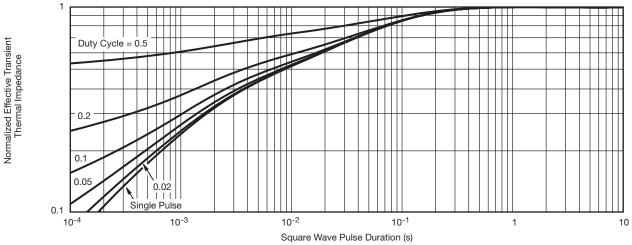
Time (s) Single Pulse Avalanche Current Capability vs. Time

10<sup>-3</sup>

10<sup>-2</sup>

10-4

Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case



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